

# DATA SHEET

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## **74AHC2G125; 74AHCT2G125** Bus buffer/line driver; 3-state

Product specification

2004 Jan 13

## Bus buffer/line driver; 3-state

## 74AHC2G125; 74AHCT2G125

## FEATURES

- Symmetrical output impedance
- High noise immunity
- ESD protection:
  - HBM EIA/JESD22-A114-A exceeds 2000 V
  - MM EIA/JESD22-A115-A exceeds 200 V
  - CDM EIA/JESD22-C101 exceeds 1000 V.
- Low power dissipation
- Balanced propagation delays
- SOT505-2 and SOT765-1 package
- Specified from –40 to +85 °C and –40 to +125 °C.

## DESCRIPTION

The 74AHC2G/AHCT2G125 is a high-speed Si-gate CMOS device.

The 74AHC2G/AHCT2G125 provides a dual non-inverting buffer/line driver with 3-state output. The 3-state output is controlled by the output enable input ( $n\overline{OE}$ ). A HIGH at pin  $n\overline{OE}$  causes the output to assume a high-impedance OFF-state.

## QUICK REFERENCE DATA

GND = 0 V;  $T_{amb} = 25\text{ °C}$ ;  $t_r = t_f \leq 3.0\text{ ns}$ .

SYMBOL	PARAMETER	CONDITIONS	TYPICAL		UNIT
			AHC2G	AHCT2G	
$t_{PHL}/t_{PLH}$	propagation delay nA to nY	$C_L = 15\text{ pF}$ ; $V_{CC} = 5\text{ V}$	3.4	3.4	ns
$C_I$	input capacitance		1.5	1.5	pF
$C_{PD}$	power dissipation capacitance	$C_L = 50\text{ pF}$ ; $f = 1\text{ MHz}$ ; notes 1 and 2	9	11	pF

## Notes

1.  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

$f_i$  = input frequency in MHz;

$f_o$  = output frequency in MHz;

$C_L$  = output load capacitance in pF;

$V_{CC}$  = supply voltage in Volts;

$N$  = total load switching outputs;

$\sum(C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

2. The condition is  $V_I = \text{GND to } V_{CC}$ .

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## FUNCTION TABLE

See note 1.

INPUT		OUTPUT
$\overline{\text{nOE}}$	nA	nY
L	L	L
L	H	H
H	X	Z

## Note

1. H = HIGH voltage level;  
L = LOW voltage level;  
X = don't care;  
Z = high-impedance OFF-state.

## ORDERING INFORMATION

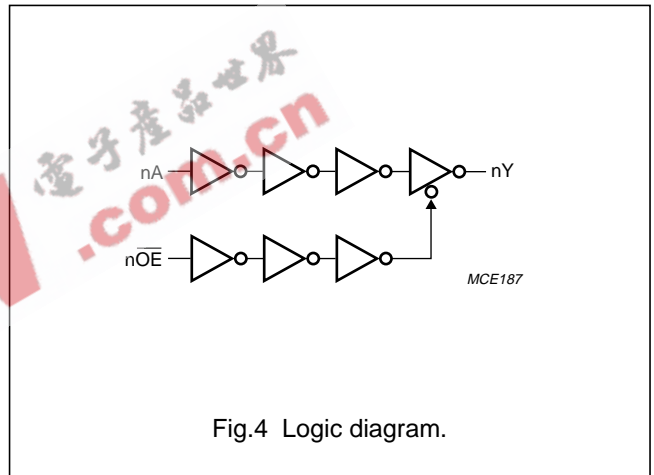
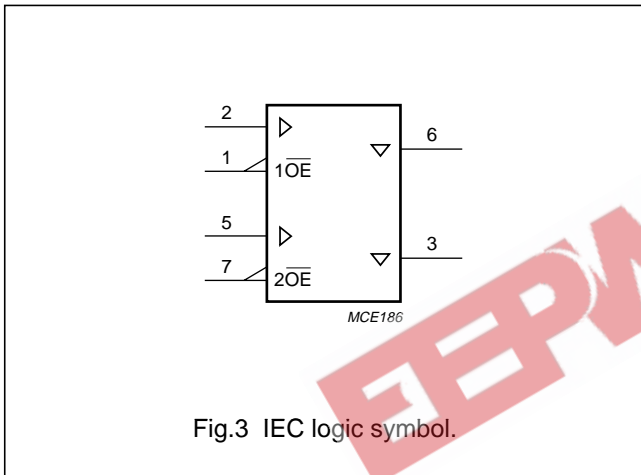
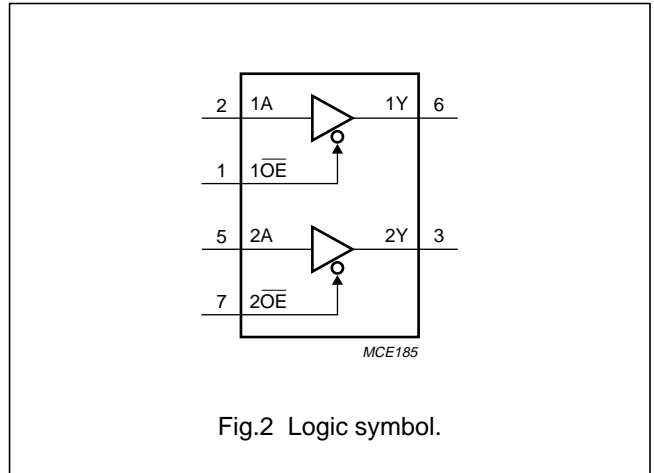
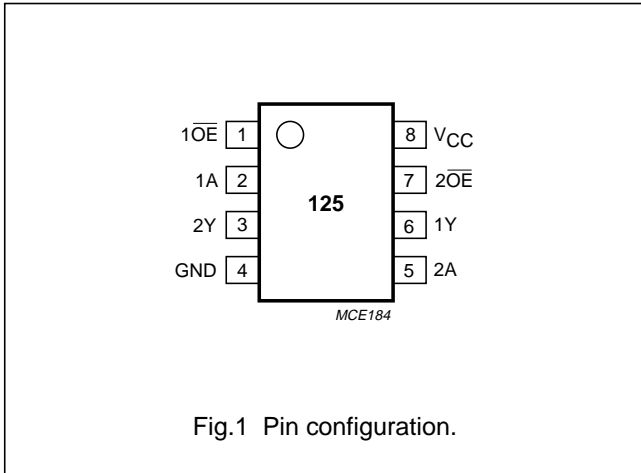
TYPE NUMBER	PACKAGE					
	TEMPERATURE RANGE	PINS	PACKAGE	MATERIAL	CODE	MARKING
74AHC2G125DP	-40 to +125 °C	8	TSSOP8	plastic	SOT505-2	A25
74AHCT2G125DP	-40 to +125 °C	8	TSSOP8	plastic	SOT505-2	C25
74AHC2G125DC	-40 to +125 °C	8	VSSOP8	plastic	SOT765-1	A25
74AHCT2G125DC	-40 to +125 °C	8	VSSOP8	plastic	SOT765-1	C25

## PINNING

PIN	SYMBOL	DESCRIPTION
1	1OE	output enable input (active LOW)
2	1A	data input
3	2Y	data output
4	GND	ground (0 V)
5	2A	data input
6	1Y	data output
7	2OE	output enable input (active LOW)
8	V <sub>CC</sub>	supply voltage

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## Bus buffer/line driver; 3-state

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## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	74AHC2G125			74AHCT2G125			UNIT
			MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
$V_{CC}$	supply voltage		2.0	5.0	5.5	4.5	5.0	5.5	V
$V_I$	input voltage		0	–	5.5	0	–	5.5	V
$V_O$	output voltage		0	–	$V_{CC}$	0	–	$V_{CC}$	V
$T_{amb}$	operating ambient temperature	see DC and AC characteristics per device	–40	+25	+125	–40	+25	+125	°C
$t_r, t_f$	input rise and fall times	$V_{CC} = 3.3 \pm 0.3$ V	–	–	100	–	–	–	ns/V
		$V_{CC} = 5 \pm 0.5$ V	–	–	20	–	–	20	ns/V

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CC}$	supply voltage		–0.5	+7.0	V
$V_I$	input voltage		–0.5	+7.0	V
$I_{IK}$	input diode current	$V_I < -0.5$ V	–	–20	mA
$I_{OK}$	output diode current	$V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V; note 1	–	$\pm 20$	mA
$I_O$	output source or sink current	$-0.5$ V $< V_O < V_{CC} + 0.5$ V	–	$\pm 25$	mA
$I_{CC}, I_{GND}$	$V_{CC}$ or GND current		–	$\pm 75$	mA
$T_{stg}$	storage temperature		–65	+150	°C
$P_{tot}$	power dissipation	$T_{amb} = -40$ to $+125$ °C	–	250	mW

## Note

1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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## DC CHARACTERISTICS

## Type 74AHC2G125

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS		MIN.	TYP.	MAX.	UNIT
		OTHER	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = 25 °C</b>							
V <sub>IH</sub>	HIGH-level input voltage		2.0	1.5	–	–	V
			3.0	2.1	–	–	V
			5.5	3.85	–	–	V
V <sub>IL</sub>	LOW-level input voltage		2.0	–	–	0.5	V
			3.0	–	–	0.9	V
			5.5	–	–	1.65	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = –50 µA	2.0	1.9	2.0	–	V
		I <sub>O</sub> = –50 µA	3.0	2.9	3.0	–	V
		I <sub>O</sub> = –50 µA	4.5	4.4	4.5	–	V
		I <sub>O</sub> = –4.0 mA	3.0	2.58	–	–	V
		I <sub>O</sub> = –8.0 mA	4.5	3.94	–	–	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = 50 µA	2.0	–	0	0.1	V
		I <sub>O</sub> = 50 µA	3.0	–	0	0.1	V
		I <sub>O</sub> = 50 µA	4.5	–	0	0.1	V
		I <sub>O</sub> = 4.0 mA	3.0	–	–	0.36	V
		I <sub>O</sub> = 8.0 mA	4.5	–	–	0.36	V
I <sub>oz</sub>	3-state output OFF-state current	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5	–	–	0.25	µA
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5	–	–	0.1	µA
I <sub>CC</sub>	quiescent supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0	5.5	–	–	1.0	µA
C <sub>I</sub>	input capacitance		–	–	1.5	10	pF

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SYMBOL	PARAMETER	CONDITIONS		MIN.	TYP.	MAX.	UNIT
		OTHER	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = -40 to +85 °C</b>							
V <sub>IH</sub>	HIGH-level input voltage		2.0	1.5	–	–	V
			3.0	2.1	–	–	V
			5.5	3.85	–	–	V
V <sub>IL</sub>	LOW-level input voltage		2.0	–	–	0.5	V
			3.0	–	–	0.9	V
			5.5	–	–	1.65	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = -50 µA	2.0	1.9	–	–	V
		I <sub>O</sub> = -50 µA	3.0	2.9	–	–	V
		I <sub>O</sub> = -50 µA	4.5	4.4	–	–	V
		I <sub>O</sub> = -4.0 mA	3.0	2.48	–	–	V
		I <sub>O</sub> = -8.0 mA	4.5	3.8	–	–	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = 50 µA	2.0	–	–	0.1	V
		I <sub>O</sub> = 50 µA	3.0	–	–	0.1	V
		I <sub>O</sub> = 50 µA	4.5	–	–	0.1	V
		I <sub>O</sub> = 4.0 mA	3.0	–	–	0.44	V
		I <sub>O</sub> = 8.0 mA	4.5	–	–	0.44	V
I <sub>oz</sub>	3-state output OFF-state current	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5	–	–	2.5	µA
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5	–	–	1.0	µA
I <sub>CC</sub>	quiescent supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0	5.5	–	–	10	µA
C <sub>I</sub>	input capacitance		–	–	–	10	pF

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SYMBOL	PARAMETER	CONDITIONS		MIN.	TYP.	MAX.	UNIT
		OTHER	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = -40 to +125 °C</b>							
V <sub>IH</sub>	HIGH-level input voltage		2.0	1.5	–	–	V
			3.0	2.1	–	–	V
			5.5	3.85	–	–	V
V <sub>IL</sub>	LOW-level input voltage		2.0	–	–	0.5	V
			3.0	–	–	0.9	V
			5.5	–	–	1.65	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = -50 μA	2.0	1.9	–	–	V
		I <sub>O</sub> = -50 μA	3.0	2.9	–	–	V
		I <sub>O</sub> = -50 μA	4.5	4.4	–	–	V
		I <sub>O</sub> = -4.0 mA	3.0	2.40	–	–	V
		I <sub>O</sub> = -8.0 mA	4.5	3.70	–	–	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = 50 μA	2.0	–	–	0.1	V
		I <sub>O</sub> = 50 μA	3.0	–	–	0.1	V
		I <sub>O</sub> = 50 μA	4.5	–	–	0.1	V
		I <sub>O</sub> = 4.0 mA	3.0	–	–	0.55	V
		I <sub>O</sub> = 8.0 mA	4.5	–	–	0.55	V
I <sub>oz</sub>	3-state output OFF-state current	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5	–	–	10	μA
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5	–	–	2.0	μA
I <sub>CC</sub>	quiescent supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0	5.5	–	–	40	μA
C <sub>I</sub>	input capacitance		–	–	–	10	pF



## Bus buffer/line driver; 3-state

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## Type 74AHCT2G125

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS		MIN.	TYP.	MAX.	UNIT
		OTHER	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = 25 °C</b>							
V <sub>IH</sub>	HIGH-level input voltage		4.5 to 5.5	2.0	–	–	V
V <sub>IL</sub>	LOW-level input voltage		4.5 to 5.5	–	–	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = –50 µA	4.5	4.4	4.5	–	V
		I <sub>O</sub> = –8.0 mA	4.5	3.94	–	–	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = 50 µA	4.5	–	0	0.1	V
		I <sub>O</sub> = 8.0 mA	4.5	–	–	0.36	V
I <sub>OZ</sub>	3-state output OFF-state current	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5	–	–	0.25	µA
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	5.5	–	–	0.1	µA
I <sub>CC</sub>	quiescent supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0	5.5	–	–	1.0	µA
ΔI <sub>CC</sub>	additional quiescent supply current per input pin	V <sub>I</sub> = 3.4 V; other inputs at V <sub>CC</sub> or GND; I <sub>O</sub> = 0	5.5	–	–	1.35	mA
C <sub>I</sub>	input capacitance			–	1.5	10	pF
<b>T<sub>amb</sub> = –40 to +85 °C</b>							
V <sub>IH</sub>	HIGH-level input voltage		4.5 to 5.5	2.0	–	–	V
V <sub>IL</sub>	LOW-level input voltage		4.5 to 5.5	–	–	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = –50 µA	4.5	4.4	–	–	V
		I <sub>O</sub> = –8.0 mA	4.5	3.8	–	–	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>O</sub> = 50 µA	4.5	–	–	0.1	V
		I <sub>O</sub> = 8.0 mA	4.5	–	–	0.44	V
I <sub>OZ</sub>	3-state output OFF-state current	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5	–	–	2.5	µA
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	5.5	–	–	1.0	µA
I <sub>CC</sub>	quiescent supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0	5.5	–	–	10	µA
ΔI <sub>CC</sub>	additional quiescent supply current per input pin	V <sub>I</sub> = 3.4 V; other inputs at V <sub>CC</sub> or GND; I <sub>O</sub> = 0	5.5	–	–	1.5	mA
C <sub>I</sub>	input capacitance		–	–	–	10	pF

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SYMBOL	PARAMETER	CONDITIONS		MIN.	TYP.	MAX.	UNIT
		OTHER	V <sub>CC</sub> (V)				
<b>T<sub>amb</sub> = -40 to +125 °C</b>							
V <sub>IH</sub>	HIGH-level input voltage		4.5 to 5.5	2.0	–	–	V
V <sub>IL</sub>	LOW-level input voltage		4.5 to 5.5	–	–	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	4.5	4.4	–	–	V
		I <sub>O</sub> = -50 μA I <sub>O</sub> = -8.0 mA	4.5	3.70	–	–	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	4.5	–	–	0.1	V
		I <sub>O</sub> = 50 μA I <sub>O</sub> = 8.0 mA	4.5	–	–	0.55	V
I <sub>OZ</sub>	3-state output OFF-state current	V <sub>I</sub> = V <sub>CC</sub> or GND	5.5	–	–	10	μA
I <sub>LI</sub>	input leakage current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	5.5	–	–	2.0	μA
I <sub>CC</sub>	quiescent supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0	5.5	–	–	40	μA
ΔI <sub>CC</sub>	additional quiescent supply current per input pin	V <sub>I</sub> = 3.4 V; other inputs at V <sub>CC</sub> or GND; I <sub>O</sub> = 0	5.5	–	–	1.5	mA
C <sub>I</sub>	input capacitance		–	–	–	10	pF

## Bus buffer/line driver; 3-state

## 74AHC2G125; 74AHCT2G125

## AC CHARACTERISTICS

## Type 74AHC2G125

GND = 0 V;  $t_r = t_f \leq 3.0$  ns.

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
		WAVEFORMS	$C_L$ (pF)				
<b><math>T_{amb} = 25\text{ }^\circ\text{C}</math></b>							
<b><math>V_{CC} = 3.0</math> to <math>3.6</math> V; note 1</b>							
$t_{PHL}/t_{PLH}$	propagation delay nA to nY	see Figs 5 and 7	15	–	4.7	8.0	ns
$t_{PZH}/t_{PZL}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	15	–	5.0	8.0	ns
$t_{PHZ}/t_{PLZ}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	15	–	6.0	9.7	ns
$t_{PHL}/t_{PLH}$	propagation delay nA to nY	see Figs 5 and 7	50	–	6.6	11.5	ns
$t_{PZH}/t_{PZL}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	50	–	6.9	11.5	ns
$t_{PHZ}/t_{PLZ}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	50	–	8.3	13.2	ns
<b><math>V_{CC} = 4.5</math> to <math>5.5</math> V; note 2</b>							
$t_{PHL}/t_{PLH}$	propagation delay nA to nY	see Figs 5 and 7	15	–	3.4	5.5	ns
$t_{PZH}/t_{PZL}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	15	–	3.6	5.1	ns
$t_{PHZ}/t_{PLZ}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	15	–	4.1	6.8	ns
$t_{PHL}/t_{PLH}$	propagation delay nA to nY	see Figs 5 and 7	50	–	4.8	7.5	ns
$t_{PZH}/t_{PZL}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	50	–	4.9	7.5	ns
$t_{PHZ}/t_{PLZ}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	50	–	5.7	8.8	ns
<b><math>T_{amb} = -40</math> to <math>+85\text{ }^\circ\text{C}</math></b>							
<b><math>V_{CC} = 3.0</math> to <math>3.6</math> V; note 1</b>							
$t_{PHL}/t_{PLH}$	propagation delay nA to nY	see Figs 5 and 7	15	1.0	–	9.5	ns
$t_{PZH}/t_{PZL}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	15	1.0	–	9.5	ns
$t_{PHZ}/t_{PLZ}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	15	1.0	–	11.5	ns
$t_{PHL}/t_{PLH}$	propagation delay nA to nY	see Figs 5 and 7	50	1.0	–	13.0	ns
$t_{PZH}/t_{PZL}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	50	1.0	–	13.0	ns
$t_{PHZ}/t_{PLZ}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	50	1.0	–	15.0	ns
<b><math>V_{CC} = 4.5</math> to <math>5.5</math> V; note 2</b>							
$t_{PHL}/t_{PLH}$	propagation delay nA to nY	see Figs 5 and 7	15	1.0	–	6.5	ns
$t_{PZH}/t_{PZL}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	15	1.0	–	6.0	ns
$t_{PHZ}/t_{PLZ}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	15	1.0	–	8.0	ns
$t_{PHL}/t_{PLH}$	propagation delay nA to nY	see Figs 5 and 7	50	1.0	–	8.5	ns
$t_{PZH}/t_{PZL}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	50	1.0	–	8.5	ns
$t_{PHZ}/t_{PLZ}$	propagation delay $n\overline{OE}$ to nY	see Figs 6 and 7	50	1.0	–	10.0	ns

## Bus buffer/line driver; 3-state

## 74AHC2G125; 74AHCT2G125

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
		WAVEFORMS	C <sub>L</sub> (pF)				
<b>T<sub>amb</sub> = -40 to +125 °C</b>							
<b>V<sub>CC</sub> = 3.0 to 3.6 V; note 1</b>							
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay nA to nY	see Figs 5 and 7	15	1.0	–	11.5	ns
t <sub>PZH</sub> /t <sub>PZL</sub>	propagation delay n $\overline{O\!E}$ to nY	see Figs 6 and 7	15	1.0	–	11.5	ns
t <sub>PHZ</sub> /t <sub>PLZ</sub>	propagation delay n $\overline{O\!E}$ to nY	see Figs 6 and 7	15	1.0	–	12.5	ns
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay nA to nY	see Figs 5 and 7	50	1.0	–	14.5	ns
t <sub>PZH</sub> /t <sub>PZL</sub>	propagation delay n $\overline{O\!E}$ to nY	see Figs 6 and 7	50	1.0	–	14.5	ns
t <sub>PHZ</sub> /t <sub>PLZ</sub>	propagation delay n $\overline{O\!E}$ to nY	see Figs 6 and 7	50	1.0	–	16.5	ns
<b>V<sub>CC</sub> = 4.5 to 5.5 V; note 2</b>							
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay nA to nY	see Figs 5 and 7	15	1.0	–	7.0	ns
t <sub>PZH</sub> /t <sub>PZL</sub>	propagation delay n $\overline{O\!E}$ to nY	see Figs 6 and 7	15	1.0	–	6.5	ns
t <sub>PHZ</sub> /t <sub>PLZ</sub>	propagation delay n $\overline{O\!E}$ to nY	see Figs 6 and 7	15	1.0	–	8.5	ns
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay nA to nY	see Figs 5 and 7	50	1.0	–	9.5	ns
t <sub>PZH</sub> /t <sub>PZL</sub>	propagation delay n $\overline{O\!E}$ to nY	see Figs 6 and 7	50	1.0	–	9.5	ns
t <sub>PHZ</sub> /t <sub>PLZ</sub>	propagation delay n $\overline{O\!E}$ to nY	see Figs 6 and 7	50	1.0	–	11.0	ns

**Notes**

1. All typical values are measured at V<sub>CC</sub> = 3.3 V.
2. All typical values are measured at V<sub>CC</sub> = 5.0 V.

**Type 74AHCT2G125**GND = 0 V; t<sub>r</sub> = t<sub>f</sub> ≤ 3.0 ns.

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
		WAVEFORMS	C <sub>L</sub> (pF)				
<b>T<sub>amb</sub> = 25 °C</b>							
<b>V<sub>CC</sub> = 4.5 to 5.5 V; note 1</b>							
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay nA to nY	see Figs 5 and 7	15	–	3.4	5.5	ns
t <sub>PZH</sub> /t <sub>PZL</sub>	propagation delay n $\overline{O\!E}$ to nY	see Figs 6 and 7	15	–	3.9	5.1	ns
t <sub>PHZ</sub> /t <sub>PLZ</sub>	propagation delay n $\overline{O\!E}$ to nY	see Figs 6 and 7	15	–	4.5	6.8	ns
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay nA to nY	see Figs 5 and 7	50	–	4.8	7.5	ns
t <sub>PZH</sub> /t <sub>PZL</sub>	propagation delay n $\overline{O\!E}$ to nY	see Figs 6 and 7	50	–	5.1	7.5	ns
t <sub>PHZ</sub> /t <sub>PLZ</sub>	propagation delay n $\overline{O\!E}$ to nY	see Figs 6 and 7	50	–	6.1	8.8	ns
<b>T<sub>amb</sub> = -40 to +85 °C</b>							
<b>V<sub>CC</sub> = 4.5 to 5.5 V</b>							
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay nA to nY	see Figs 5 and 7	15	1.0	–	6.5	ns
t <sub>PZH</sub> /t <sub>PZL</sub>	propagation delay n $\overline{O\!E}$ to nY	see Figs 6 and 7	15	1.0	–	6.0	ns
t <sub>PHZ</sub> /t <sub>PLZ</sub>	propagation delay n $\overline{O\!E}$ to nY	see Figs 6 and 7	15	1.0	–	8.0	ns
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay nA to nY	see Figs 5 and 7	50	1.0	–	8.5	ns

Bus buffer/line driver; 3-state

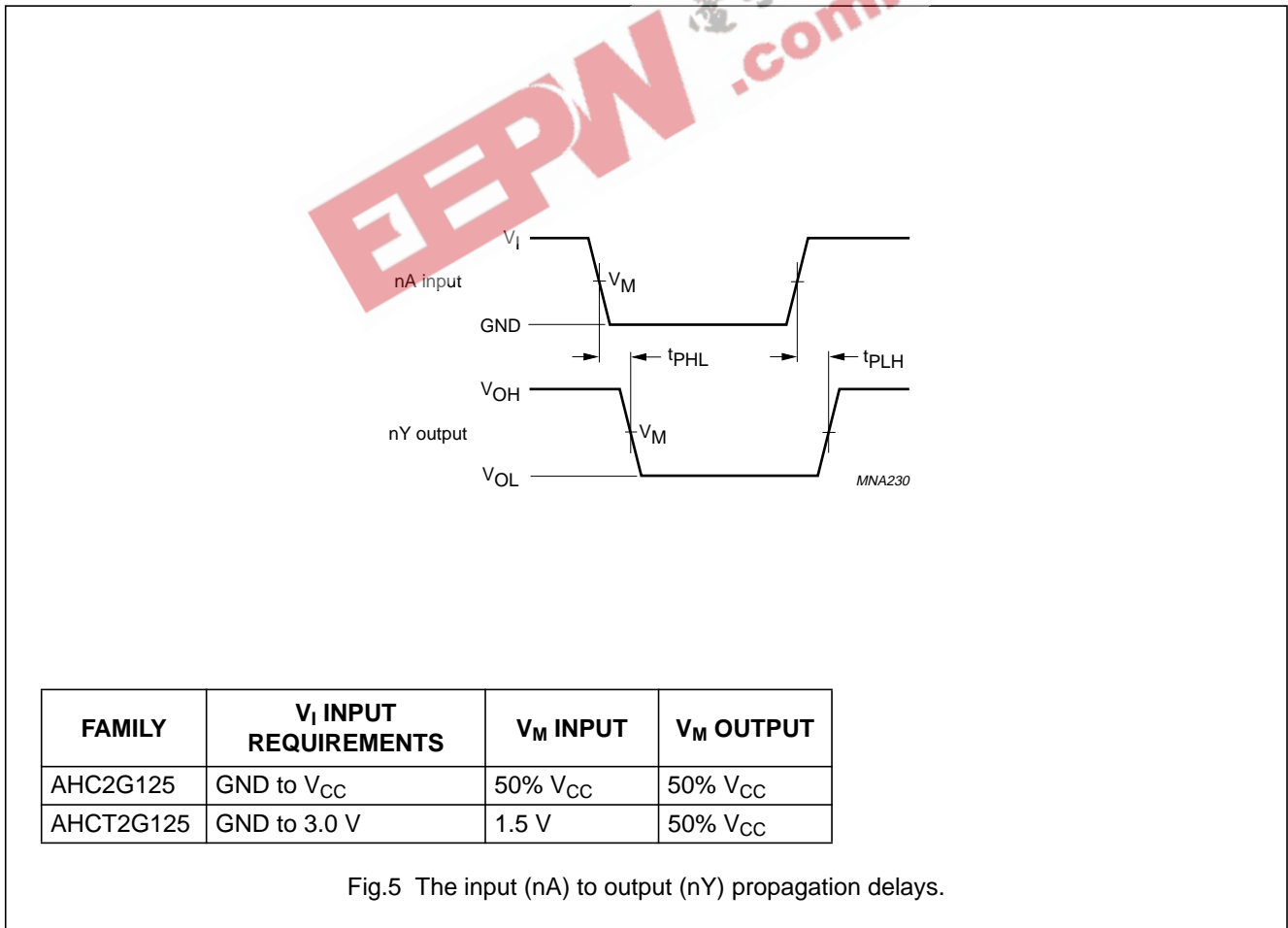
74AHC2G125; 74AHCT2G125

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
		WAVEFORMS	C <sub>L</sub> (pF)				
t <sub>PZH</sub> /t <sub>PZL</sub>	propagation delay n $\overline{O\bar{E}}$ to nY	see Figs 6 and 7	50	1.0	–	8.5	ns
t <sub>PHZ</sub> /t <sub>PLZ</sub>	propagation delay n $\overline{O\bar{E}}$ to nY	see Figs 6 and 7	50	1.0	–	10.0	ns
<b>T<sub>amb</sub> = –40 to +125 °C</b>							
<b>V<sub>CC</sub> = 4.5 to 5.5 V</b>							
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay nA to nY	see Figs 5 and 7	15	1.0	–	6.5	ns
t <sub>PZH</sub> /t <sub>PZL</sub>	propagation delay n $\overline{O\bar{E}}$ to nY	see Figs 6 and 7	15	1.0	–	6.0	ns
t <sub>PHZ</sub> /t <sub>PLZ</sub>	propagation delay n $\overline{O\bar{E}}$ to nY	see Figs 6 and 7	15	1.0	–	8.0	ns
t <sub>PHL</sub> /t <sub>PLH</sub>	propagation delay nA to nY	see Figs 5 and 7	50	1.0	–	8.5	ns
t <sub>PZH</sub> /t <sub>PZL</sub>	propagation delay n $\overline{O\bar{E}}$ to nY	see Figs 6 and 7	50	1.0	–	8.5	ns
t <sub>PHZ</sub> /t <sub>PLZ</sub>	propagation delay n $\overline{O\bar{E}}$ to nY	see Figs 6 and 7	50	1.0	–	10.0	ns

Note

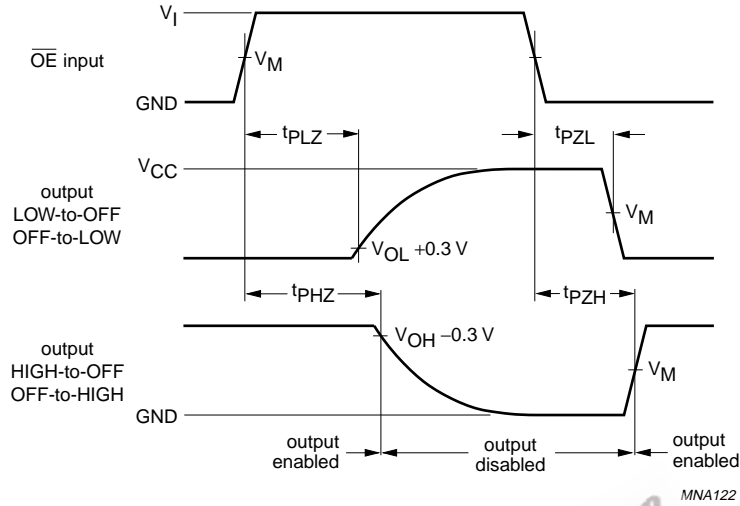
1. All typical values are measured at V<sub>CC</sub> = 5.0 V.

AC WAVEFORMS



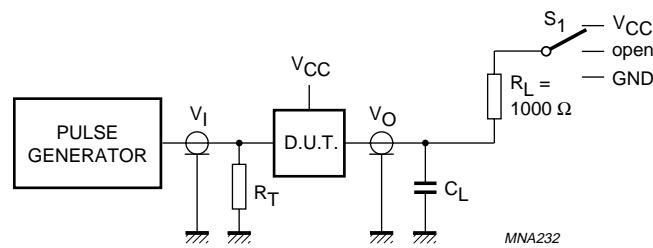
Bus buffer/line driver; 3-state

74AHC2G125; 74AHCT2G125



FAMILY	V <sub>I</sub> INPUT REQUIREMENTS	V <sub>M</sub> INPUT	V <sub>M</sub> OUTPUT
AHC2G125	GND to V <sub>CC</sub>	50% V <sub>CC</sub>	50% V <sub>CC</sub>
AHCT2G125	GND to 3.0 V	1.5 V	50% V <sub>CC</sub>

Fig.6 The 3-state enable and disable times.



TEST	S <sub>1</sub>
t <sub>PLH</sub> /t <sub>PHL</sub>	open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>CC</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

Definitions for test circuit:

R<sub>L</sub> = load resistance.

C<sub>L</sub> = load capacitance including jig and probe capacitance (see Chapter "AC characteristics" for the value).

R<sub>T</sub> = termination resistance should be equal to the output impedance Z<sub>o</sub> of the pulse generator.

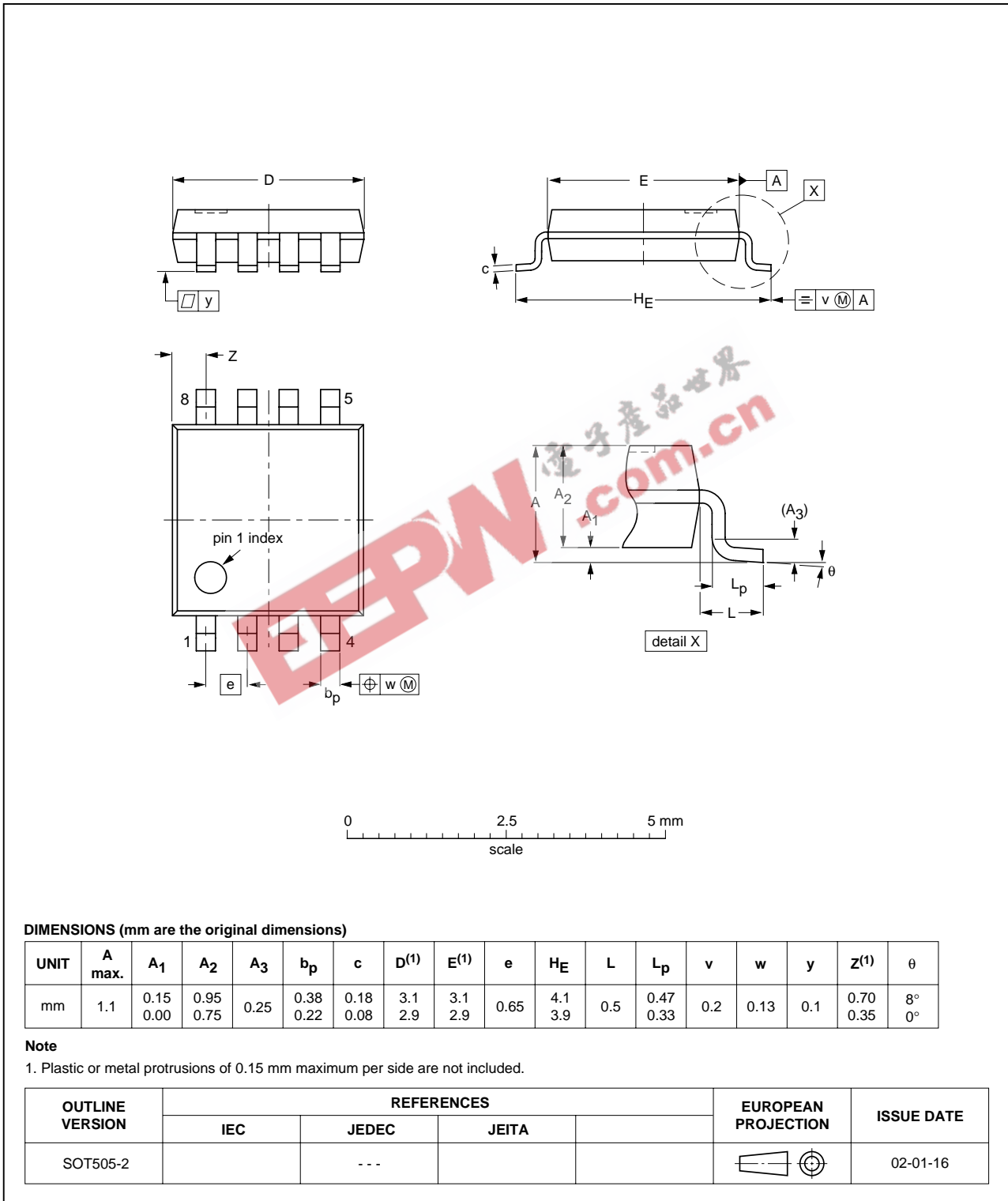
Fig.7 Load circuitry for switching times.

Bus buffer/line driver; 3-state

74AHC2G125; 74AHCT2G125

PACKAGE OUTLINES

TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm; lead length 0.5 mm SOT505-2

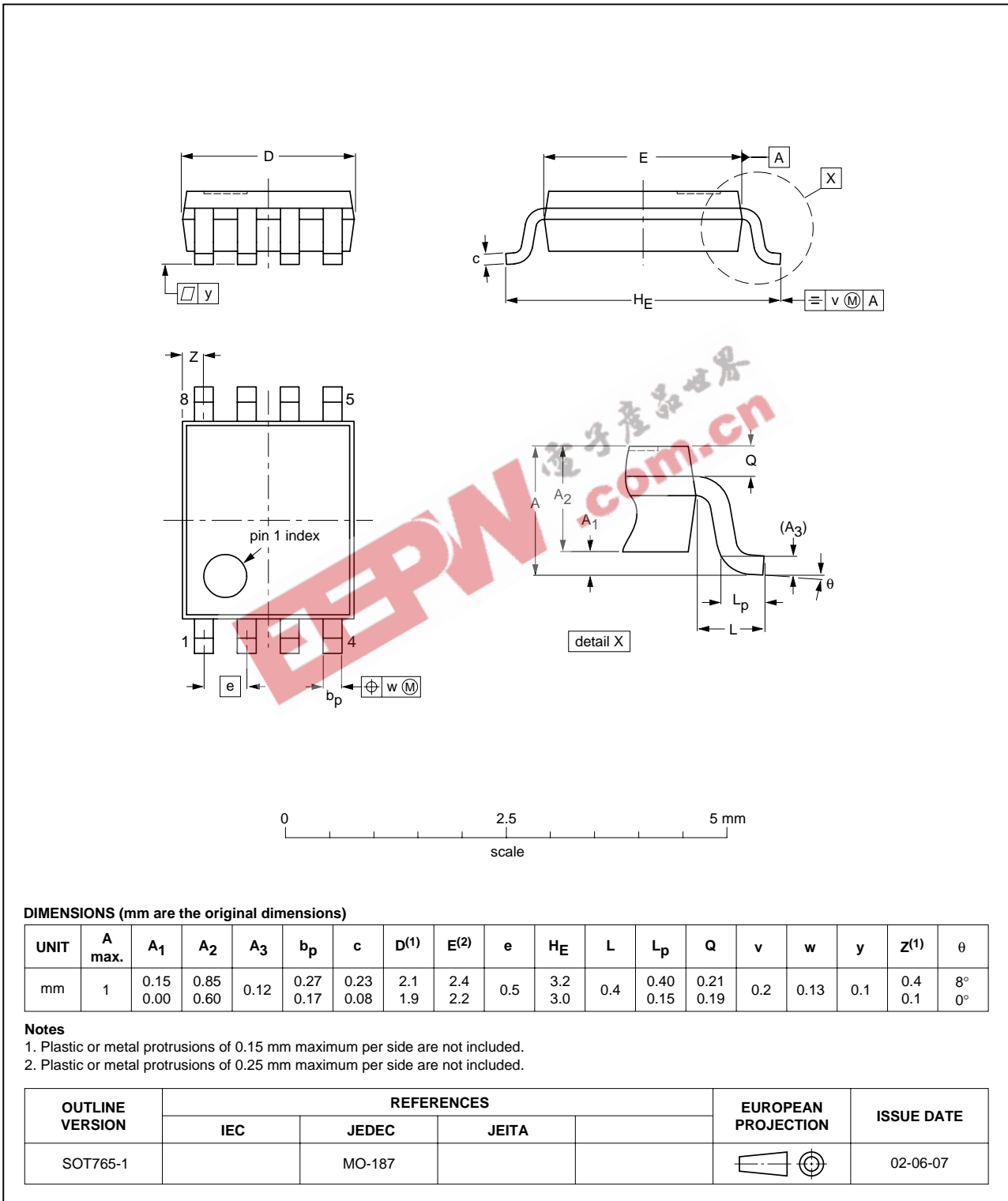


Bus buffer/line driver; 3-state

74AHC2G125; 74AHCT2G125

VSSOP8: plastic very thin shrink small outline package; 8 leads; body width 2.3 mm

SOT765-1





## Bus buffer/line driver; 3-state

## 74AHC2G125; 74AHCT2G125

## DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
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